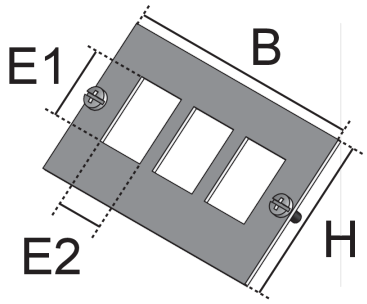


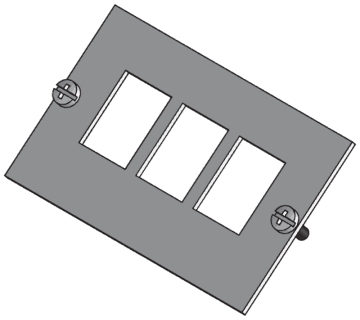
UDEP AMP

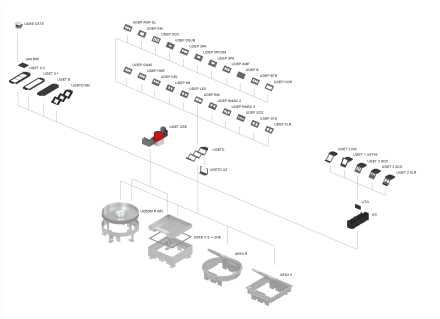
Mounting board, data technology

UDEP AMP components are installation boards from the underfloor system range. The boards are bolted into data device carriers and are used to accommodate a maximum of 3 AMP Corning data jacks FutureCom™ S1200 module Cat.7A from TE Connectivity or the TERA® 4-Pair Outlets made by Sieman. The installation boards are made of aluminium with a black coating on one side and have the installation dimensions of E1 19.3 mm and E2 14.6 mm.

Artikel	Typ	H	B	data jacks	E1	E2	colour	W
UDEP-AMP 3	adapter board,	46 mm	75 mm	3	19.3 mm	14.6 mm	black	0.014 kg

DETAIL- UND ANWENDUNGSBILDER





OPTIONALES ZUBEHÖR

UGETD

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